

Features

- AEC-Q101 Qualified
- · Split Gate Trench MOSFET Technology
- · Low Thermal Resistance
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- · Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

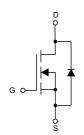
- Operating Junction Temperature Range: -55°C to +175°C
- Storage Temperature Range: -55°C to +175°C
- Thermal Resistance: 42°C/W Junction to Ambient(Note2)
- Thermal Resistance: 1.5°C/W Junction to Case

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Volltage		V _{GS}	±20	V
Continuous Drain Current	T _C =25°C	I _D	63	А
	T _C =100°C		45	
Pulsed Drain Current (Note3)		I _{DM}	252	Α
Total Power Dissipation ^(Note4)		P _D	100	W
Single Pulse Avalanche Energy (Note 5)		E _{AS}	100	mJ

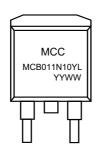
Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_D is based on max. junction temperature, using junction-case thermal resistance.
- 5. T_J =25°C, V_{DD} =40V, V_{GS} =10V, R_G =25 Ω , L=0.5mH.

⇒bhYfbU `Ghfi Whi fY`UbX`A Uf_]b['7 cXY



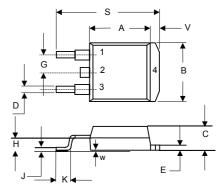
1. Gate 2,4. Drain 3. Source



4 codes in total YY is the year WW is the week

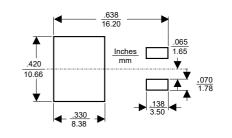
N-Channel MOSFET

D2-PAK



DIMENSIONS					
DIM INCH		HES MI		М	NOTE
DIIVI	MIN	MAX	MIN	MAX	NOTE
Α	0.331	0.370	8.40	9.40	
В	0.378	0.417	9.60	10.60	
С	0.165	0.189	4.20	4.80	
D	0.027	0.037	0.68	0.94	
Е	0.045	0.055	1.14	1.40	
G	0.1		2.	54	TYP.
Н	0.096	0.134	2.43	3.40	
J	0.011	0.025	0.28	0.64	
K	0.071	0.131	1.80	3.32	
S	0.575	0.625	14.60	15.87	
V	0.042	0.058	1.07	1.47	
W	0.000	0.010	0.00	0.25	

Suggested Solder Pad Layout





Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	100			V	
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V			1	μΑ	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1	1.7	2.5	V	
Drain-Source On-Resistance	_	V _{GS} =10V, I _D =20A		8.5	11	0	
	R _{DS(on)}	V _{GS} =4.5V, I _D =20A	11		15	– mΩ	
Gate Resistance	R_{g}	f=1 MHz, Open drain		1.2		Ω	
Diode Characteristics			'				
Continuous Body Diode Current	Is				63	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A			1.3	V	
Reverse Recovery Time	t _{rr}	1. 00A III/II 400A/		45		ns	
Reverse Recovery Charge	Q _{rr}	I _F =30A, dl/dt=100A/μs		63		nC	
Dynamic Characteristics			<u>'</u>				
Input Capacitance	C _{iss}			1404			
Output Capacitance	C _{oss}	V_{DS} =50V, V_{GS} =0V,f=1MHz		345		pF	
Reverse Transfer Capacitance	C _{rss}			2.8			
Total Gate Charge	Q_g			29.8			
Gate-Source Charge	Q_{gs}	V _{DS} =30V,V _{GS} =10V,I _D =30A		4.9		nC	
Gate-Drain Charge	Q_{gd}			8.4			
Turn-On Delay Time	t _{d(on)}			9.8			
Turn-On Rise Time	t _r	V _{DD} =30V, V _{GS} =10V,		42			
Turn-Off Delay Time	t _{d(off)}	$R_G=2.5\Omega, I_D=30A$		17.5		ns	
Turn-Off Fall Time	t _f			4.2			



Curve Characteristics

Fig.1 - Typical Output Characteristics

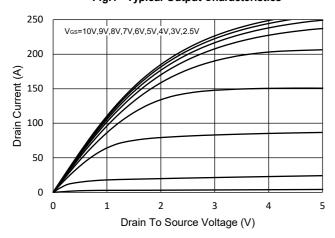


Fig.2 - Transfer Characteristic

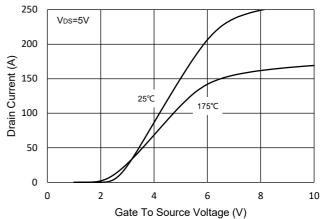


Fig.3 - $R_{\rm DS(ON)}$ - $V_{\rm GS}$

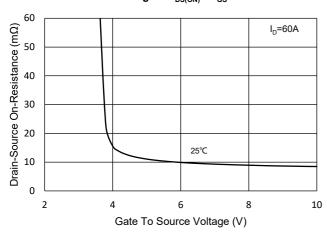


Fig.4 - $R_{\rm DS(ON)}$ - $I_{\rm D}$

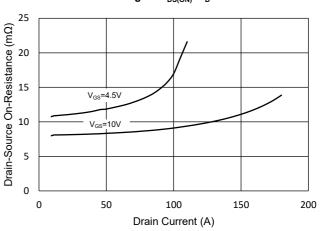


Fig.5 - Capacitance Characteristics

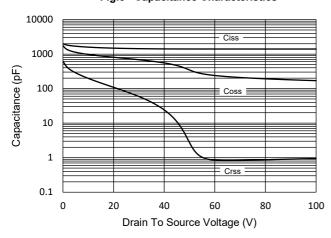
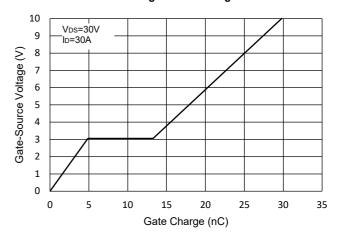
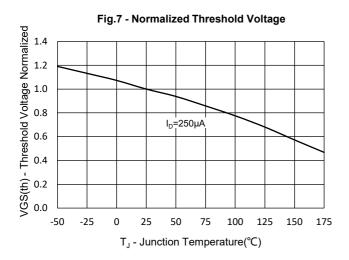


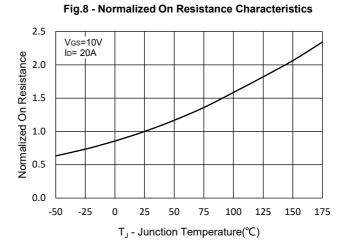
Fig.6 - Gate Charge

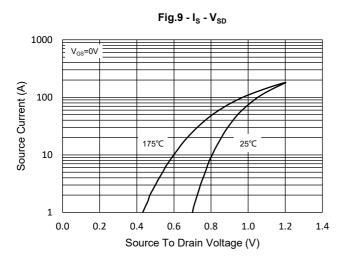


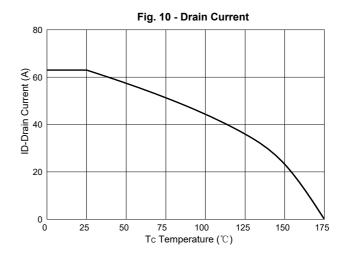


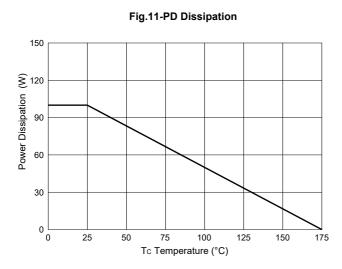
Curve Characteristics





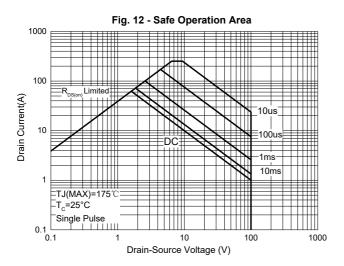


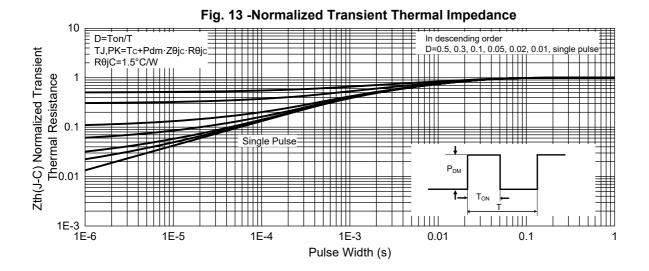






Curve Characteristics





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Ordering Information

Device	Packing	
Part Number-TP	Tape&Reel: 800pcs/Reel	

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